

### Abstract

An interconnect comprising an anisotropic conductive film and an optically transmissive unit embedded in the anisotropic conductive film. The optically transmissive unit provides an optically transmissive path through the anisotropic conductive film. In an alternative embodiment, an electronic package comprises a first substrate, a second substrate, and an interconnect located between the first substrate and the second substrate. The interconnect comprises an anisotropic conductive film for electrically coupling a first conductive element formed on the first substrate to a second conductive element formed on the second substrate and one or more optically transmissive units embedded in the anisotropic conductive film. At least one of the one or more optically transmissive units couples an optical signal path on the first substrate to an optical receiver on the second substrate.

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